



THC63LVD1027

Dual Link LVDS Repeater

General Description

The THC63LVD1027 LVDS(Low Voltage Differential Signaling) repeater is designed to support pixel data transmission between Host and Flat Panel Display up to WUXGA resolution.

THC63LVD1027 receives the dual link LVDS data streams and transmits the LVDS data through various line rate conversion modes, Dual Link Input / Dual Link Output, Single Link Input / Dual Link Output, and Dual Link Input / Single Link Output.

Features

- 30bits/pixel dual link LVDS Receiver
- 30bits/pixel dual Link LVDS Transmitter
- Operating Temperature Range : -40°C~85°C
- Wide LVDS input skew margin: ± 480ps at 75MHz
- Accurate LVDS output timing: ± 250ps at 75MHz
- Reduced swing LVDS output mode supported to suppress the system EMI
- Various line rate conversion modes supported Dual link input / Dual link output [clkout=1x clkin] Single link input / Dual link output [clkout=1/2x clkin] Dual link input / Single link output [clkout=2x clkin]
- Distribution (signal duplication) mode supported
- Power down mode supported
- 3.3V single voltage power supply
- No external components required for PLLs
- 64pin TSSOP with Exposed PAD (0.5mm lead pitch)

Block Diagram

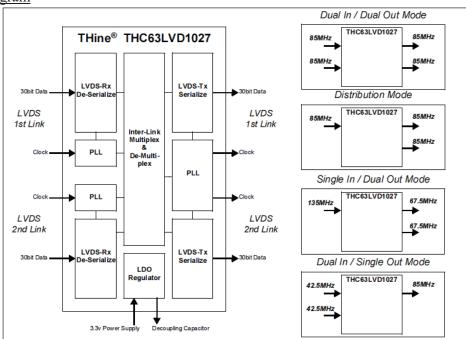
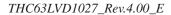


Figure 1. Block Diagram

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Pin Diagram

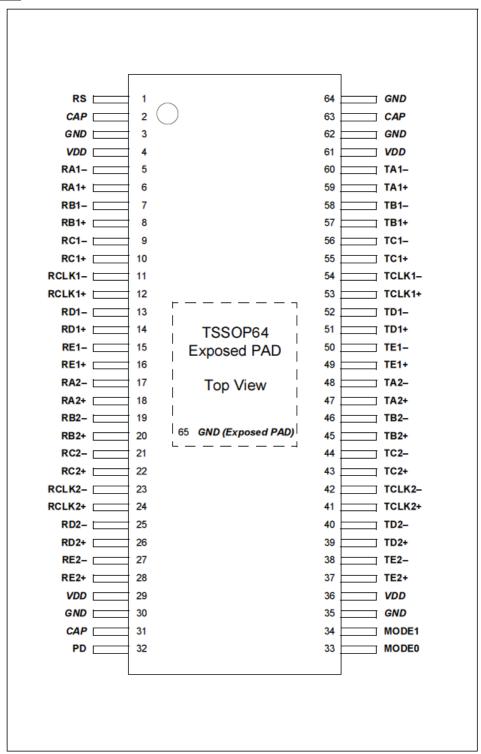
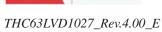


Figure 2. Pin Diagram





Pin Description

Table 1. Pin Description

Pin Name	Direction	Type			Descripti	on			
RA1+/-		<i>.</i>	LVDS data	input fo		of 1st Link			
RB1+/-	1					B of 1st Link			
RC1+/-	1					C of 1st Link			
RD1+/-	1					of 1st Link			
RE1+/-	1					E of 1st Link			
RCLK1+/-	-		LVDS clock			7 OI IST LINK			
RA2+/-						of 2nd Link			
RB2+/-	Input					B of 2nd Link			
RC2+/-	1					C of 2nd Link			
RD2+/-	-					of 2nd Link			
-	-								
RE2+/-	-		LVDS data			of 2nd Link			
RCLK2+/-						te,RCLK2+/- must be Hi-Z.			
		LVDS			ow in this page.)				
TA1+/-			LVDS data	output f	for channel	A of 1st Link			
TB1+/-	1					B of 1st Link			
TC1+/-	1					C of 1st Link			
TD1+/-	1					D of 1st Link			
TE1+/-	1		LVDS data output for channel E of 1st Link						
TCLK1+/-	1				for 1st Lin				
TA2+/-	Output					A of 2nd Link			
TB2+/-	1								
TC2+/-			LVDS data output for channel B of 2nd Link LVDS data output for channel C of 2nd Link						
TD2+/-	1					D of 2nd Link			
TE2+/-	1					E of 2nd Link			
TCLK2+/-	1				for 2nd Lir				
PD			Power Dov		101 Zhu Eh	IK .			
10			H: Normal op						
			L: Power dow	n state, all I		gnals turn to Hi-Z			
RS					level select	tion			
			H: Normal sw L: Reduced sv						
MODE1	-		Mode selec						
MODE1 MODE0	Input	LV-TTL	MODE1	MODE0	RCLK2+/-	Description			
MIODEO			L	L	Clkin	Dual-in/Dual-out mode			
			L	L	Hi-Z	Distribution mode			
			H	L	Hi-Z	Single-in/Dual-out mode			
			L H	H H	Clkin	Dual-in/Single-out mode Reserved			
					in/Dual-out mod	de, RCLK2+/- must be Hi-Z.			
VDD	1		3.3V power			ae, 100 Dist. / must be ili-2.			
GND	Power	_				also Ground)			
CAP	10,001		Decoupling			uiso Givanaj			
CAI						decoupling capacitors(Ccap).			
			Recommended			1 0 1 (1)			
L	L			15 0.1					



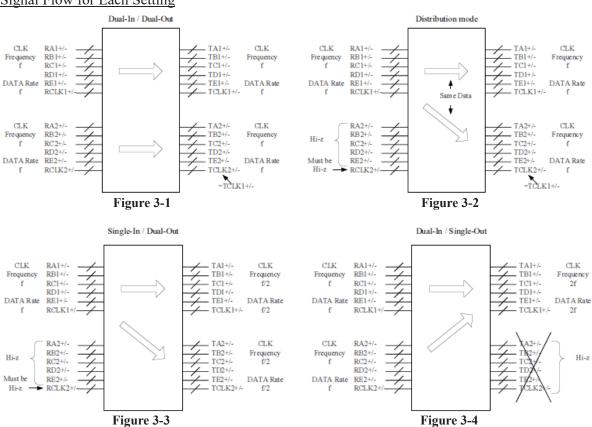


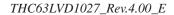
Mode Setting

Table 2. Mode Setting

Input/Output	RCLK2+/-	MODE1	MODE0
		(Input mode)	(Output mode)
		H: Single	H: Single
		L: Dual	L: Dual
Dual-In/Dual-Out	CLK in	L	L
(Fig.3-1,14-1)			
Distribution	Hi-Z	L	L
(Fig.3-2,14-2)			
Single-In/Dual-Out	Hi-Z	Н	L
(Fig.3-3,14-3)			
Dual-In/Single-Out	CLK in	L	Н
(Fig.3-4,14-4)			
Reserved	- -	Н	Н

Signal Flow for Each Setting







Output Control / Fail Safe

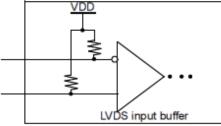
THC63LVD1027 has a function to control output depending on LVDS input condition.

Table 3. Output Control

PD	RCLK1+/-	RCLK2+/-	Output
L	*	*	All Hi-Z
Н	Hi-Z	*	All Hi-Z
Н	CLK in	CLK in	Refer to p.4 Mode Setting #
Н	CLK in	Hi-Z	Refer to p.4 Mode Setting #

^{*:} Don't care

For fail-safe purpose, all LVDS input pins are connected to VDD via resistance for detecting Hi-Z state.



Internal circuit of THC63LVD1027

Figure 4. Fail Safe Circuit

^{#:} If a particular input data pair is Hi-Z, the corresponding output data become L according to LVDS DC spec.



Absolute Maximum Ratings

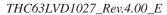
Table 4. Absolute Maximum Rating

Parameter	Min	Max	Unit
Power Supply Voltage	-0.3	+4.0	V
LVDS Input Voltage	-0.3	$V_{DD} + 0.3$	V
Junction Temperature	-	125	°C
Storage Temperature	-55	125	°C
Reflow Peak Temperature / Time	-	260 / 10sec	°C
Maximum Power Dissipation @+25°C	-	2.5	W

Operating Conditions

Table 5. Operating Condition

Table 3. Operating Condition								
Symbol	Paramete	er	Min	Тур	Max	Unit		
Ta	Operating Ambient Temperature		-40	25	+85	°C		
V _{DD}	Power Supply Voltag	ge	3.0	3.3	3.6	V		
	Dual-In/Dual-Out	Input	20	-	85	MHz		
	Duai-III/Duai-Out	Output	20	-	85	MITZ		
	Distribution	Input	20	-	85	MHz		
TF.	Distribution	Output	20	-	85	MITIZ		
$\mathbf{F_{clk}}$	Simple In/Duel Out	Input	40	-	135	MHz		
	Single-In/Dual-Out	Output	20	-	67.5	MITZ		
	D 11/C: 1 0 /	Input	20	-	42.5	MII-		
	Dual-In/Single-Out Output		40	_	85	MHz		





Power Consumption

Table 6. Power Consumption

Symbol	Parameter		Conditions		Min	Тур.	Max	Unit
			CLKIN=40MHz		-	-	265	
		Dual-In/Dual-Out	CLKIN=65MHz		-	-	305	
		Duai-in/Duai-Out	CLKIN=75MHz		-	-	325	mA
			CLKIN=85MHz		-	-	340	
		Distribution	CLKIN=40MHz		-	-	215	
			CLKIN=65MHz		-	-	235	4
One			CLKIN=75MHz	$R_{L Tx}=100\Omega$	-	-	245	mA
	Operating Current		CLKIN=85MHz	CL=5pF RS=VDD Fig 6.	-	-	260	Í I
т	(Worst Case Pattern)	G. 1 1 10 10 1	CLKIN=40MHz		-	-	175	
I_{CCW}			CLKIN=65MHz		-	-	190	1
	Fig 5.		CLKIN=75MHz		-	-	200	mA
		Single-In/Dual-Out	CLKIN=85MHz		-	-	210	
			CLKIN=112MHz		-	-	230	
			CLKIN=135MHz		-	-	250	1
			CLKIN=20MHz		-	-	215	
		Decel In/Sin-1- Out	CLKIN=32.5MHz		-	-	235	mA
		Dual-In/Single-Out	CLKIN=37.5MHz		-	-	245	
			CLKIN=42.5MHz		-	-	260	
I _{CCS}	Power Down Current	-	-	-	-	-	8	mA

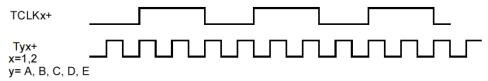


Figure 5. Test Pattern (LVDS Output Full Toggle Pattern)

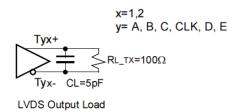


Figure 6. LVDS Output Load





Electrical Characteristics

DC Specifications

Table 7. DC Specifications

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V_{CAP}	Capacitor pin appearance voltage	C _{CAP} =0.1μF	-	1.8	-	V
V_{IL}	LV-TTL Input Low Voltage	-	GND	-	0.8	V
V_{IH}	LV-TTL Input High Voltage	-	2.0	-	VDD	V
I_{IN_TTL}	LV-TTL Input Leakage Current	-	-4	-	+4	μΑ

LVDS Receiver DC Specifications

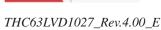
Table 8. LVDS Receiver DC Specifications

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V _{IN_RX}	LVDS-Rx Input Voltage Range	-	0.3	-	2.1	V
V _{IC_RX}	LVDS-Rx Common Voltage	-	0.6	1.2	1.8	V
V _{TH_RX}	LVDS-Rx Differential High Threshold	N 1 2N	-	-	+100	
V _{TL_RX}	LVDS-Rx Differential Low Threshold	$V_{IC_RX} = 1.2V$	-100	-	-	mV
$ V_{ID_RX} $	LVDS-Rx Differential Input Voltage	-	100	-	600	
		PD=VDD	-0.3	-	+0.3	mA
I _{IN_RX}	LVDS-Rx Input Leakage Current	PD=GND Vin=GND or VDD	-10	-	+10	μΑ

LVDS Transmitter DC Specifications

Table 9. LVDS Transmitter DC Specifications

Symbol	Parameter	(Conditions	Min	Тур	Max	Unit		
V _{OC_TX}	LVDS-Tx Common Voltage		-	1.125	1.25	1.375	V		
ΔV_{OC_TX}	Change in VOC between complementary output states	R	D -	D	-	-	-	35	mV
18.7	LVDS-Tx Differential Output Threshold	$R_{L_TX} =$	Normal Swing	250	350	450	mV		
$ V_{OD_TX} $		100Ω	Reduced Swing	100	200	300	III V		
ΔV_{OD_TX}	Change in VOD between complementary output states		-	-	-	35	mV		
I _{OS_TX}	LVDS-Tx Output Short Current	V _{DD} =3.3V	V _{out} =GND	-24	-	-	mA		
I _{OZ_TX}	LVDS-Tx Output Tri-state Current	PD=GND	V _{out} =GND to VDD	-10	-	+10	μΑ		





AC Specifications

Table 10. AC Specifications

Symbol	Parameter	Cond	itions	Min	Тур	Max	Unit
$t_{\rm LT}$	Phase Lock Loop Set Time (Fig 7.)	-	-	-	-	10	ms
		Dual-In/Dual-Out	CLKIN=75MHz	$9t_{RCP}+3$	9t _{RCP} +5	9t _{RCP} +7	
4 Detail atomic (Fig. 9)	Distribution	CLKIN=75MHz	9t _{RCP} +3	9t _{RCP} +5	9t _{RCP} +7		
$t_{ m DL}$	Data Latency (Fig 8.)	Single-In/Dual-Out	CLKIN=75MHz	(11+2/7)t _{RCP} +3	(11+2/7)t _{RCP} +5	(11+2/7)t _{RCP} +7	ns
		Dual-In/Single-Out	CLKIN=37.5MHz	(11+2/7)t _{RCP} +3	(11+2/7)t _{RCP} +5	(11+2/7)t _{RCP} +7	
t _{DEH}	DE Input High Time (Fig 9.)		-	$2t_{RCP}$	-	-	
t _{DEL}	DE Input Low Time (Fig 9.)	Single-In/Dual-Out	-	$2t_{RCP}$	-	-	ns
t _{DEINT}	DE Input Period (Fig 9.)		-	4t _{RCP}	Must be 2n t _{RCP} (n=integer)	-	

AC Timing Diagrams

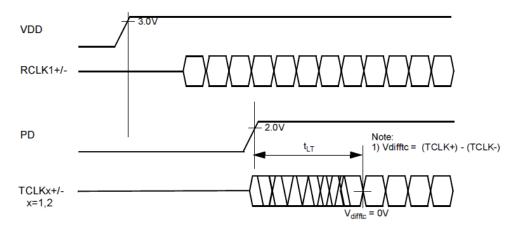


Figure 7. Phase Lock Loop Set Time





AC Timing Diagrams(Continued)

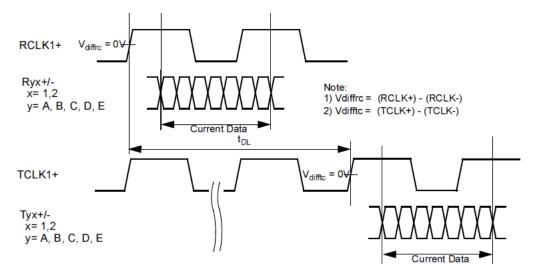


Figure 8. DATA Latency

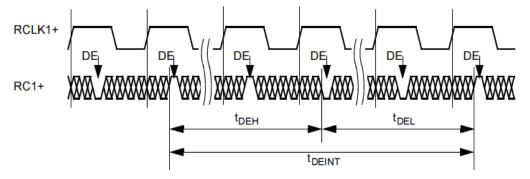
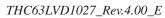


Figure 9. Single Link Input / Dual Link Output Mode RC1(DE) Input Timing





LVDS Receiver AC Specifications

Table 11. LVDS Receiver AC Specifications

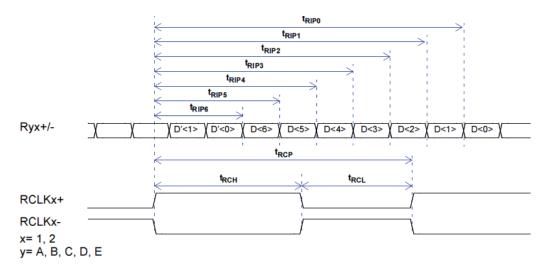
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
t_{RCP}	LVDS Clock Period	-	7.4	-	50	
$t_{ m RCH}$	LVDS Clock High Duration	-	2/7t _{RCP}	$4/7t_{RCP}$	5/7t _{RCP}	ns
$t_{ m RCL}$	LVDS Clock Low Duration	-	$2/7t_{RCP}$	$3/7t_{RCP}$	5/7t _{RCP}	
		CLKIN=75MHz ⁽¹⁾	480	-	-	
t_{RSUP}	LVDS Data Input Setup Margin	CLKIN=112MHz ⁽¹⁾	250	-	-	ps
		CLKIN=135MHz ⁽¹⁾	220	-	-	
		CLKIN=75MHz ⁽¹⁾	480	-	-	
$t_{ m RHLD}$	LVDS Data Input Hold Margin	CLKIN=112MHz ⁽¹⁾	250	-	-	ps
		CLKIN=135MHz ⁽¹⁾	220	-	-	
t _{RIP6}	LVDS Data Input Position 6	-	$2/7t_{RCP}$ - t_{RHLD}	$2/7t_{RCP}$	2/7t _{RCP} +t _{RSUP}	
t_{RIP5}	LVDS Data Input Position 5	-	$3/7t_{RCP}$ - t_{RHLD}	$3/7t_{RCP}$	$3/7t_{RCP}+t_{RSUP}$	
t _{RIP4}	LVDS Data Input Position 4	-	4/7t _{RCP} -t _{RHLD}	$4/7t_{RCP}$	4/7t _{RCP} +t _{RSUP}	
t _{RIP3}	LVDS Data Input Position 3	-	5/7t _{RCP} -t _{RHLD}	5/7t _{RCP}	5/7t _{RCP} +t _{RSUP}	ps
t _{RIP2}	LVDS Data Input Position 2	-	6/7t _{RCP} -t _{RHLD}	6/7t _{RCP}	6/7t _{RCP} +t _{RSUP}	
t _{RIP1}	LVDS Data Input Position 1	-	7/7t _{RCP} -t _{RHLD}	7/7t _{RCP}	$7/7t_{RCP}+t_{RSUP}$	
$t_{ m RIP0}$	LVDS Data Input Position 0	-	8/7t _{RCP} -t _{RHLD}	$8/7t_{RCP}$	8/7t _{RCP} +t _{RSUP}	
t _{CK12}	Skew Time Between RCLK1 and RCLK2	-	-0.3 t _{RCP}	-	+0.3 t _{RCP}	ps

⁽¹⁾ $V_{IC_RX}=1.2V$, $t_{RCH}=4/7$ t_{RCP}





LVDS Receiver Input Timing



Ry1+/- skew margin is the one between RCLK1+/- and Ry1+/-. Ry2+/- skew margin is the one between RCLK2+/- and Ry2+/-.

Figure 10. LVDS Receiver Timing

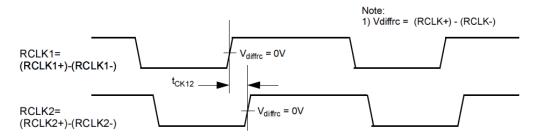


Figure 11. Skew time between RCLK1 and RCLK2





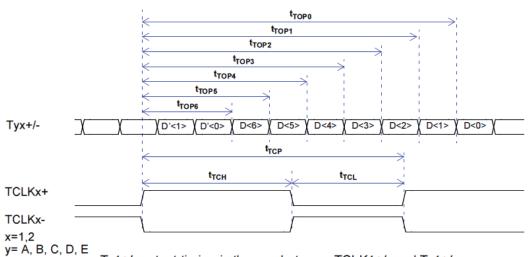
LVDS Transmitter AC Specifications

Table 12. LVDS Transmitter AC Specifications

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
t _{TCP}	LVDS Clock Period	-	11.76	-	50	
t _{TCH}	LVDS Clock High Duration	-	-	4/7t _{TCP}	-	ns
t_{TCL}	LVDS Clock Low Duration	-	-	3/7t _{TCP}	-	
t_{TSUP}	LVDS Data Output Setup	CLKOUT=75MHz	-	-	250	ps
t_{THLD}	LVDS Data Output Hold	CLKOUT=75MHz	-	-	250	ps
t _{TOP6}	LVDS Data Output Position 6	-	$2/7t_{TCP}$ - t_{THLD}	2/7t _{TCP}	$2/7t_{TCP}+t_{TSUP}$	
t _{TOP5}	LVDS Data Output Position 5	-	$3/7t_{TCP}$ - t_{THLD}	$3/7t_{TCP}$	$3/7t_{TCP}+t_{TSUP}$	
t _{TOP4}	LVDS Data Output Position 4	-	4/7t _{TCP} -t _{THLD}	4/7t _{TCP}	4/7t _{TCP} +t _{TSUP}	
t _{TOP3}	LVDS Data Output Position 3	-	5/7t _{TCP} -t _{THLD}	5/7t _{TCP}	5/7t _{TCP} +t _{TSUP}	ps
t _{TOP2}	LVDS Data Output Position 2	-	6/7t _{TCP} -t _{THLD}	6/7t _{TCP}	6/7t _{TCP} +t _{TSUP}	
t _{TOP1}	LVDS Data Output Position 1	-	7/7t _{TCP} -t _{THLD}	7/7t _{TCP}	$7/7t_{TCP} + t_{TSUP}$	
t _{TOP0}	LVDS Data Output Position 0	-	8/7t _{TCP} -t _{THLD}	8/7t _{TCP}	8/7t _{TCP} +t _{TSUP}	
t _{LVT}	LVDS Transition Time (Fig 13.)	Fig.6	-	0.6	1.5	ns



LVDS Transmitter Output Diagram



Ty1+/- output timing is the one between TCLK1+/- and Ty1+/-. Ty2+/- output timing is the one between TCLK2+/- and Ty2+/-.

Figure 12. LVDS Transmitter Timing

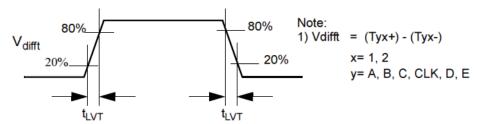


Figure 13. LVDS Transition Timing

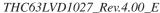


LVDS Data Mapping **Dual-In / Dual-Out** LVDS-Rx Input Mapping RCLK1+ RA1+/-G1 [4] X R1 [9] R1 [8] R1 [7] R1 [6] R1 [5] R1 [4] G3 [4] R3 [9] X R3 [8] X R3 [7] X R3 [6] X R3 [5] X R3 [4] RB1+/-G1 [8] X G1 [7] X G1 [6] X G1 [5] X B3 [5] X B3 [4] X G3 [9] X G3 [8] X G3 [7] X G3 [6] X G3 [5] B1 [5] X B1 [4] X G1 [9] X RC1+/-| VSYNC | HSYNC | B1 [9] | B1 [8] | B1 [7] | B1 [6] | DE VSYNC | HSYNC | B3 [9] | B3 [8] | B3 [7] | B3 [6] RD1+/-G1 [3] X G1 [2] X R1 [3] X R1 [2] X data11 B1 [3] B1 [2] data11 B3 [3] B3 [2] G3 [3] (G3 [2]) R3 [3] R3 [2] RE1+/data12 B1 [1] B1 [0] G1 [1] X G1 [0] X R1 [1] X R1 [0] X data12 B3 [1] X B3 [0] X G3 [1] G3 [0] R3 [1] R3 [0] RCLK2+ RA2+/-G2 [4] R2 [9] R2 [8] R2 [7] X R2 [6] X R2 [5] X R2 [4] G4 [4] R4 [9] \ R4 [8] R4 [7] X R4 [6] X R4 [5] RB2+/-B2 [5] B2 [4] G2 [9] G2 [8] G2 [7] G2 [6] R2 [5] B4 [5] B4 [4] G4 [9] G4 [8] G4 [7] RC2+/-VSYNC HSYNC B2 [9] Y B2 [8] B2 [7] B2 [6] DE VSYNC HSYNC B4 [9] B4 [8] RD2+/data21 B2 [3] B2 [2] G2 [3] G2 [2] R2 [3] R2 [2] data21 B4 [3] B4 [2] G4 [3] G4 [2] R4 [3] R4 [2] RE2+/data22 B2 [1] B2 [0] G2 [1] Y G2 [0] Y R2 [1] R2 [0] data22 B4 [1] B4 [0] G4 [1] LVDS-Tx Output Mapping TCLK1+ TA1+/-R1 [8] \ R1 [7] \ R1 [6] \ R1 [5] \ R1 [4] \ G3 [4] \ R3 [9] \ R3 [8] \ R3 [7] \ R3 [6] \ R3 [5] \ R3 [4] G1 [4] X R1 [9] X TB1+/-B1 [5] Y B1 [4] G1 [9] G1 [8] X G1 [7] X G1 [6] X G1 [5] X B3 [5] B3 [4] \ G3 [9] \ G3 [8] G3 [7] G3 [6] G3 [5] TC1+/-DE VSYNC HSYNC B1 [9] X B1 [8] X B1 [7] X B1 [6] DE VSYNC HSYNC B3 [9] X B3 [8] X B3 [7] X B3 [6] TD1+/data11 | B1 [3] | B1 [2] G1 [3] X G1 [2] X R1 [3] X R1 [2] X data 11 B3 [3] B3 [2] X G3 [3] (G3 [2]) R3 [3] X R3 [2] TE1+/data12 B1 [1] B1 [0] G1 [1] G1 [0] R1 [1] R1 [0] data12 B3 [1] B3 [0] G3 [1] G3 [0] R3 [1] TCLK2+ R4 [6] Y TA2+/-R2 [8] R2 [7] R2 [6] R2 [5] R2 [4] G4 [4] R4 [9] R4 [8] R4 [7] R4 [5] G2 [4] R2 [9] TB2+/-G2 [9] G2 [8] Y G2 [7] G2 [5] B4 [5] G2 [6] B4 [4] G4 [9] G4 [8] G4 [7] G4 [6] G4 [5] TC2+/-VSYNC HSYNC B2 [9] B2 [8] B2 [7] B2 [6] DE VSYNC HSYNC B4 [9] B4 [8] B4 [7] B4 [6] TD2+/data21 B2 [2] G2 [3] G2 [2] R2 [3] R2 [2] data21 B4 [3] B4 [2] G4 [3] R4 [3] TE2+/data22 B2 [1] B2 [0] G2 [1] G2 [0] R2 [1] R2 [0] data22 B4 [1] B4 [0] G4 [1] G4 [0] R4 [1]

Data bits "data11, data12, data21, data22" are available for additional data transmission.

Figure 14-1. Data Mapping for Dual-In/Dual-Out

(Regardless of the Data Latency)





Distribution Mode

In Distribution mode, RCLK2+/- must be Hi-Z.

LVDS-Rx Input Mapping RCLK1+ RA1+/-G1 [4] R1 [9] \ R1 [8] R1 [7] X R1 [6] R1 [5] R1 [4] G2 [4] R2 [9] R2 [7] R2 [6] R2 [8] X R2 [5] R2 [4] RB1+/-B1 [5] B1 [4] G1 [9] G1 [8] G1 [7] G1 [6] G1 [5] B2 [5] B2 [4] G2 [9] G2 [8] G2 [7] G2 [6] G2 [5] RC1+/-DE VSYNC HSYNC B1 [9] X B1 [8] X B1 [7] X B1 [6] DE VSYNC | HSYNC | B2 [9] | B2 [8] | B2 [7] B2 [6] RD1+/-B2 [3] R1 [2] data11 R2 [3] data11 B1 [3] B1 [2] G1 [3] (G1 [2]) R1 [3] B2 [2] G2 [3] G2 [2] R2 [2] RE1+/data12 B1 [1] B1 [0] G1 [1] X G1 [0] X R1 [1] X R1 [0] data12 B2 [1] X G2 [1] G2 [0] R2 [1]) B2 [0] X R2 [0] RCLK2+ Hi-Z RA2+/no care RB2+/no care RC2+/no care RD2+/no care no care RE2+/-LVDS-Tx Output Mapping TCLK1+ TA1+/-G1 [4] X R1 [9] X R1 [8] X R1 [7] X R1 [6] X R1 [5] X R1 [4] X G2 [4] X R2 [9] X R2 [8] X R2 [7] X R2 [6] X R2 [5] X R2 [4] TB1+/-B1 [5] X B1 [4] G1 [9] G1 [8] X G1 [7] X G1 [6] X G1 [5] X B2 [5] X B2 [4] \(G2 [9] \(G2 [8] \(G2 [7] \) G2 [6] G2 [5] TC1+/-DE VSYNC HSYNC B1 [9] X B1 [8] X B1 [7] X B1 [6] DE VSYNC HSYNC B2 [9] B2 [8] B2 [7] X B2 [6] TD1+/data11 B1 [3] R1 [3] R1 [2] B2 [3] B1 [2] G1 [3] X G1 [2] X data11 B2 [2] G2 [3] G2 [2] R2 [3] R2 [2] TE1+/data12 B1 [1] B1 [0] G1 [1] (G1 [0]) R1 [1] X R1 [0] data12 B2 [1] B2 [0] G2 [1] G2 [0] R2 [1] R2 [0] TCLK2+ TA2+/-G1 [4] R1 [9] R1 [8] R1 [7] X R1 [6] R1 [5] R1 [4] G2 [4] R2 [9] R2 [8] X R2 [7] X R2 [6] R2 [5] R2 [4] TB2+/-B1 [5] B1 [4] G1 [9] G1 [8] G1 [7] G1 [6] G1 [5] B2 [5] B2 [4] G2 [9] G2 [8] G2 [7] G2 [6] G2 [5] TC2+/-DE VSYNC **HSYNC** B1 [9] (B1 [8]) B1 [7] B1 [6] DE VSYNC HSYNC | B2 [9] | B2 [8] B2 [7] B2 [6] TD2+/-R1 [2] data11 data11 B1 [3] B1 [2] G1 [3] (G1 [2]) R1 [3] B2 [3] B2 [2] G2 [3] G2 [2] R2 [3] \ R2 [2] TE2+/-B1 [1] G1 [1] \ G1 [0] \ R1 [1] R1 [0] data12 | B2 [1] B2 [0] | G2 [1] | G2 [0] R2 [1] \ (Regardless of the Data Latency)

Data bits "data11, data12" are available for additional data transmission.

Figure 14-2. Data Mapping for Distribution mode



Single-In / Dual-Out

In Single-in / Dual-out mode, RCLK2+/- must be Hi-Z.

LVDS-Rx Input Mapping RCLK1+ RA1+/-G1 [4] \ R1 [9] \ R1 [8] \ R1 [7] \ R1 [6] \ R1 [5] \ R1 [4] \ G2 [4] \ R2 [9] R2 [8] X R2 [7] X R2 [6] R2 [5] R2 [4] RB1+/-B1 [4] \(\text{G1 [9] \(\text{G1 [8] \(\text{G1 [7] \(\text{G1 [6] \(\text{G1 [5] \(\text{B2 [5] \(\text{B2 [4] \(\text{V} \)}}\) G2 [9] X G2 [8] G2 [7] RC1+/-VSYNC HSYNC B1 [9] B1 [8] X B1 [7] B1 [6] DE VSYNC HSYNC B2 [9] B2 [8] B2 [7] RD1+/data11 B1 [2] X G1 [3] X G1 [2] X R1 [3] R1 [2] \(\text{data11} \) B2 [3] \(\text{} B2 [2] X G2 [3] G2 [2] RE1+/-B1 [1] B1 [0] G1 [1] G1 [0] X R1 [1] R1 [0] \(\text{data12} \) B2 [1] B2 [0] X G2 [1] G2 [0] R2 [1] R2 [0] data12 RCLK2+ Hi-Z RA2+/no care RB2+/no care RC2+/no care RD2+/no care RE2+/no care LVDS-Tx Output Mapping TCLK1+ TA1+/-G1 [4] R1 [9] R1 [8] R1 [7] R1 [6] R1 [5] R1 [4] TB1+/-B1 [5] B1 [4] G1 [9] G1 [8] G1 [7] G1 [6] G1 [5] TC1+/-VSYNC DE **HSYNC** B1 [9] B1 [8] B1 [7] B1 [6] TD1+/-R1 [3] data11 B1 [3] B1 [2] G1 [3] G1 [2] R1 [2] TE1+/data12 B1 [1] B1 [0] G1 [1] G1 [0] R1 [1] R1 [0]

Data bits "data11, data12" are available for additional data transmission.

R2 [7]

G2 [8]

B2 [9]

G2 [3]

G2 [1]

R2 [6]

G2 [7]

B2 [8]

G2 [2]

G2 [0]

R2 [5]

G2 [6]

B2 [7]

R2 [3]

R2 [1]

(Regardless of the Data Latency)

R2[8]

G2 [9]

HSYNC

B2 [2]

B2 [0]

Figure 14-3(a). Data Mapping for Single-In/Dual-Out

G2 [4]

B2 [5]

DE

data11

data12

R2 [9]

B2 [4]

VSYNC

B2 [3]

B2 [1]

TCLK2+ TA2+/-

TB2+/-

TC2+/-

TD2+/-

TE2+/-

R2 [4]

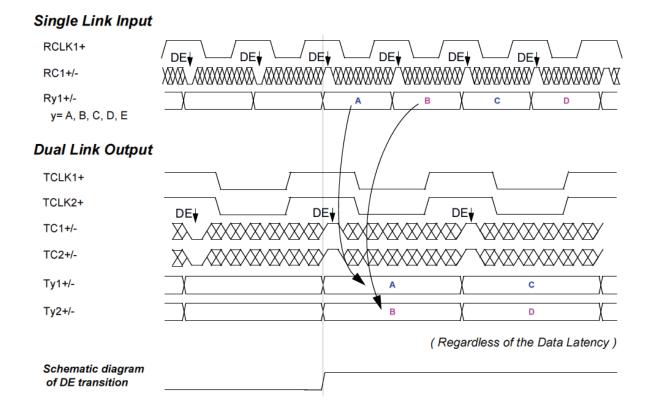
G2 [5]

B2 [6]

R2 [2]

R2 [0]





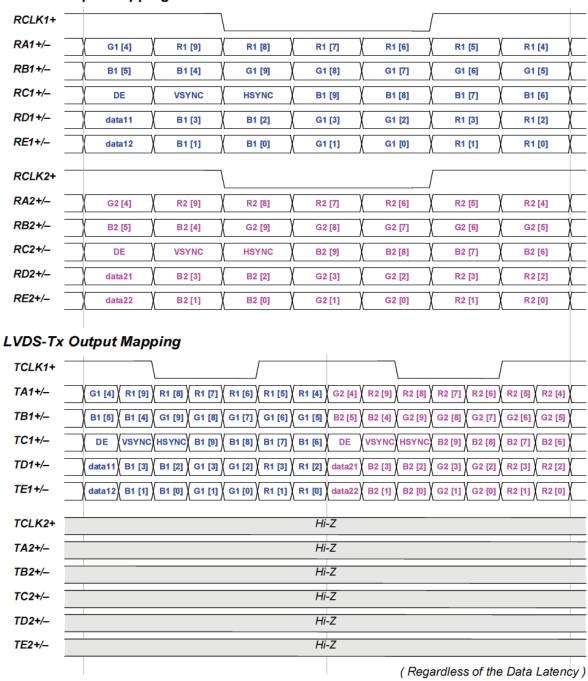
Single-in / Dual-out mode uses DE signal L-to-H-edge to start distribution of input data.

Figure 14-3(b). Data Mapping for Single-In/Dual-Out



Dual-In / Single-Out

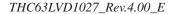
LVDS-Rx Input Mapping



Data bits "data11, data12, data21, data22" are available for additional data transmission.

Figure 14-4. Data Mapping for Dual-In/Single-Out

Notes





1) LVDS input pin connection

When LVDS line is not derived from the previous device, the line is pulled up to 3.3V internally in THC63LVD1027. This can cause violation of absolute maximum ratings to the previous LVDS Tx device whose operating condition is lower voltage power supply than 3.3V. This phenomenon may happen at power on phase of the whole system including THC63LVD1027. One solution for this problem is PD=L control during no LVDS input period because pull-up resistors are cut off at power down state.

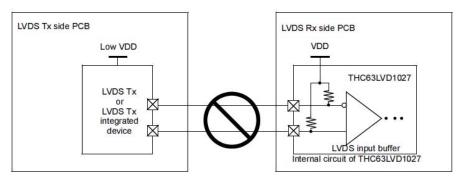


Figure 15. LVDS input pin connection

2) Power On Sequence

Don't input RCLK1+/- and RCLK2+/- before THC63LVD1027 is on in order to keep absolute maximum ratings.

THC63LVD1027_Rev.4.00_E



3) Cable Connection and Disconnection

Don't connect and disconnect the LVDS cable, when the power is supplied to the system.

4)GND Connection

Connect the each GND of the PCB which Transmitter, Receiver and THC63LVD1027 on it. It is better for EMI reduction to place GND cable as close to LVDS cable as possible.

5) Multi Drop Connection

Multi drop connection is not recommended.

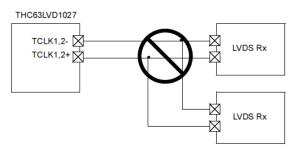


Figure 16.Multi Drop Connection

6) Asynchronous use

Asynchronous use such as following systems are not recommended. Page.11 tCK12 spec should be kept.

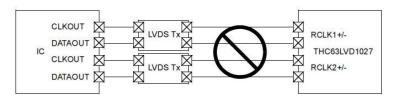


Figure 17-1. Asynchronous Use1

Asynchronous use such as following systems are not recommended.

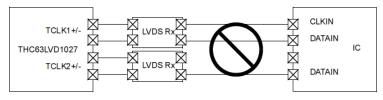
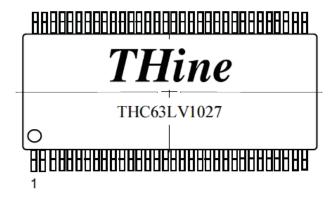


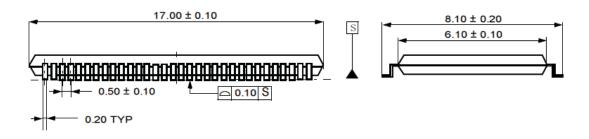
Figure 17-2. Asynchronous Use2

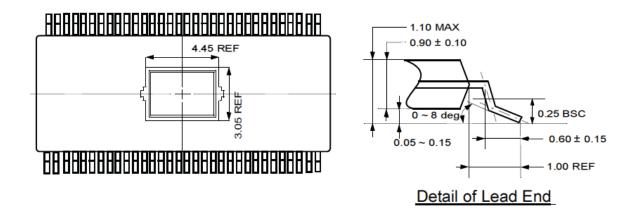




Package







Exposed PAD is GND and must be soldered to PCB.

Figure 18. Package Diagram

Unit: mm





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- 2. The circuit diagrams described in this material are examples of the application which may not always apply to the customer's design. We are not responsible for possible errors and omissions in this material. Please note if errors or omissions should be found in this material, we may not be able to correct them immediately.
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